

Electronic Patent Application Fee Transmittal

| Application Number: | 10049270 | | | | | | | | |
|--|--|----------|--------|----------------------|-------------|----------|----------|--------|----------------------|
| Filing Date: | 27-Jun-2002 | | | | | | | | |
| Title of Invention: | MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST COMPOSITION, METHOD FOR MANUFACTURING MULTILAYER PRINTED WIRING BOARD, AND SEMICONDUCTOR DEVICE | | | | | | | | |
| First Named Inventor/Applicant Name: | Hui Zhong | | | | | | | | |
| Filer: | Marvin Jay Spivak/Dalibor Tudman | | | | | | | | |
| Attorney Docket Number: | 312302US40PCT | | | | | | | | |
| Filed as Large Entity | | | | | | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | | | | | | |
| <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%; padding: 5px;">Description</th> <th style="width: 15%; padding: 5px;">Fee Code</th> <th style="width: 15%; padding: 5px;">Quantity</th> <th style="width: 15%; padding: 5px;">Amount</th> <th style="width: 25%; padding: 5px;">Sub-Total in USD(\$)</th> </tr> </thead> </table> | | | | | Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) | | | | | |
| Basic Filing: | | | | | | | | | |
| Pages: | | | | | | | | | |
| Claims: | | | | | | | | | |
| Miscellaneous-Filing: | | | | | | | | | |
| Petition: | | | | | | | | | |
| Patent-Appeals-and-Interference: | | | | | | | | | |
| Post-Allowance-and-Post-Issuance: | | | | | | | | | |
| Extension-of-Time: | | | | | | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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| Miscellaneous: | | | | |
| Submission- Information Disclosure Stmt | 1806 | 1 | 180 | 180 |
| Total in USD (\$) | | | | 180 |